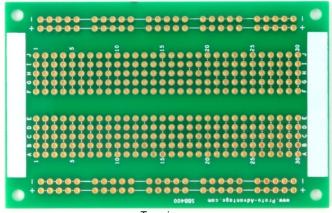
Datasheet revision 1.3

www.Proto-Advantage.com

400 pts solder-in breadboard (Exact Solderless Match)



CODESS. WES-15ED MARK-S | SACK ARE

Bottom view

Product Highlights

Immersion Gold Finish
All holes are gold plated and are on a 0.1" grid
1/16" (1.6mm) thick FR-4 UL94V-0
Accepts a variety of wire sizes (20-32 AWG)
4 mounting holes

Two rectangular silkscreen areas that you can write on using pencil or pen

Usage

This board exactly copies the routing of a 400 pts ½ size solderless breadboard.

Allows direct transfer of circuits prototyped in a solderless breadboard to a solder-in breadboard to facilitate functional insystem testing or field testing.

Specifications

Wiring Pattern: 2 Distribution Strips

1 Terminal Strip 100 Distribution Holes

300 Terminal Holes
Dimensions: 3.6" x 2.3" x 0.0625" (91.44mm x 58.42mm x 1.6mm)

PCB construction: FR-4 UL94V-0

PCB operating temperature range: -40°C to +130°C (-40°F to +266°F)

PCB reflow maximum temperature: +260°C (500°F)
PCB trace width: 0.059" (1.5mm)

PCB trace thickness: 1 oz copper / ft² (1.4 mils) (0.03556 mm)

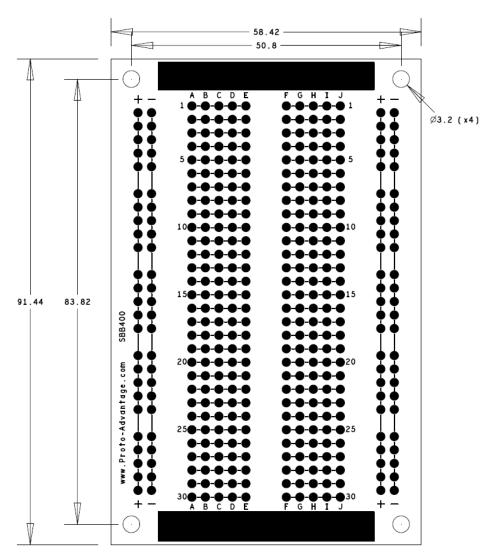
PCB trace current capacity*: 10A continuous @ 40°C rise, 13A continuous @ 80°C rise*

Recommended pin size: 25 mil square wire wrap posts or smaller

Diameter of 4 corner mounting holes: 3.2mm (125 mils)

^{*} Derived from IPC-2221 current capacity graphs at 25°C ambient temperature. Actual current capacity will vary based on air flow, component density, and other factors.

Topside silkscreen lines between holes show where bottom traces electrically connect holes.



(Representative drawing only - not to scale)